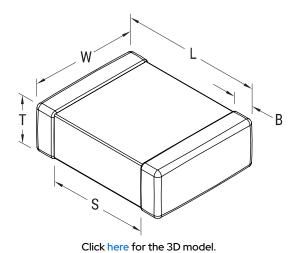


C1206C103M2TACTU

Aliases (C1206C103M2TAC7800)

SMD Comm X8G HT150C, Ceramic, 0.01 uF, 20%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	20 mg
Shelf Life	78 Weeks
MSL	1

0.01 uF

Dimensions	
Chip Size	1206
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
Т	0.9mm +/-0.10mm
S	1.5mm MIN
В	0.5mm +/-0.25mm

	•		
W	1.6mm +/-0.2mm	1.6mm +/-0.2mm	
Т	0.9mm +/-0.10mm		
S	1.5mm MIN		
В	0.5mm +/-0.25mm		
Packaging Specifications			

Packaging Packaging (

	3.2mm +/-0.2mm	Measurement Condition	1 kHz 1.0Vrms
	1.6mm +/-0.2mm	Tolerance	20%
	0.9mm +/-0.10mm	Voltage DC	200 VDC
	1.5mm MIN	Dielectric Withstanding Voltage	500 VDC
	0.5mm +/-0.25mm	Temperature Range	-55/+150°C
		Temp. Coefficient	X8G
g Specifications		Capacitance Change with	30 ppm/C, 1kHz 1.0Vrms
1	T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	
g Quantity	antity 4000	Dissipation Factor	0.1% 1 kHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
		Insulation Resistance	100 GOhms

Specifications

Capacitance

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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